SDAS069B - DECEMBER 1982 - REVISED DECEMBER 1994 ......

- Two-Way Asynchronous Communication **Between Data Buses**
- pnp Inputs Reduce dc Loading
- **Package Options Include Plastic** Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

### description

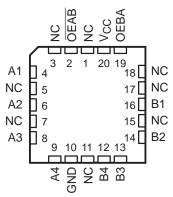
These quadruple bus transceivers are designed for asynchronous two-way communication between data buses. The control-function implementation allows for maximum flexibility in timing. These devices allow data transmission from the A bus to the B bus or from the B bus to the A bus depending upon the logic levels at the output-enable (OEBA and OEAB) inputs. The output-enable inputs can be used to disable the device so that the buses are effectively isolated.

The dual-enable configuration gives the quadruple bus transceivers the capability to store data by simultaneously enabling OEBA and OEAB. Each output reinforces its input in this transceiver configuration. When both control inputs are enabled and all other data sources to the two sets of bus lines are at high impedance, both sets of bus lines (eight in all) retain their states. The 4-bit codes appearing on the two sets of buses are identical.

SN54ALS243A J PACKAGE SN74ALS243A D OR N PACKAGE											
(TOP VIEW)											
OEAB	1 2	14 13	V <sub>CC</sub> OEBA								
A1	3	12	NC								
A2 [	4		B1 B2								
A3 [ A4 [	5 6	10 9	B2 B3								
GND [	7	8	B3 B4								

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#### SN54ALS243A . . . FK PACKAGE (TOP VIEW)



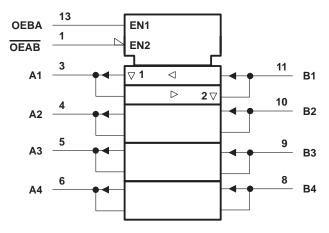
NC - No internal connection

The SN54ALS243A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS243A is characterized for operation from 0°C to 70°C.

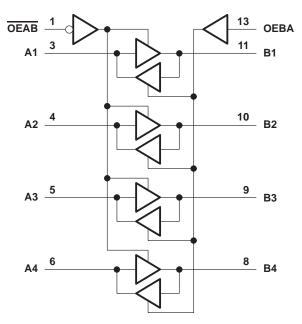
FUNCTION TABLE											
INP	UTS	FUNCTION									
OEAB	OEBA	FUNCTION									
L	L	A to B									
н	Н	B to A									
Н	L	Isolation									
L	Н	Latch A and B (A = B)									

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# logic symbol<sup>†</sup>



logic diagram (positive logic)



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

Pin numbers shown are for the D, J, and N packages.

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>‡</sup>

Supply voltage, V <sub>CC</sub>	
Input voltage, V <sub>I</sub> : All inputs	7V
I/O ports	
Operating free-air temperature range, T <sub>A</sub> : SN54ALS243A	. −55°C to 125°C
SN74ALS243A	0°C to 70°C
Storage temperature range	. −65°C to 150°C

‡ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions

		SN54ALS243A			SN7	UNIT		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
VCC	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.7			0.8	V
ЮН	High-level output current			-12			-15	mA
IOL	Low-level output current			12			24	mA
Т <sub>А</sub>	Operating free-air temperature	-55		125	0		70	°C



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PARAMETER		TEST CO	TEST CONDITIONS			3A	SN7	4ALS24	3A	UNIT
		TEST CO	MIN	TYP†	MAX	MIN	TYP†	MAX	UNIT	
VIK		V <sub>CC</sub> = 4.5 V,	lj = - 18 mA			-1.2			-1.2	V
		$V_{CC}$ = 4.5 V to 5.5 V,	I <sub>OH</sub> = -0.4 mA	V <sub>CC</sub> -2	2		V <sub>CC</sub> -2	2		
\/ <b>~</b>			I <sub>OH</sub> = -3 mA	2.4	3.2		2.4	3.2		V
VOH		$V_{CC} = 4.5 V$	I <sub>OH</sub> = -12 mA	2						V
			I <sub>OH</sub> = -15 mA				2			
V <sub>OL</sub>			I <sub>OL</sub> = 12 mA		0.25	0.4		0.25	0.4	V
		V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 24 mA					0.35	0.5	V
1.	Control inputs		V <sub>1</sub> = 7 V			0.1			0.1	mA
II.	A or B ports	V <sub>CC</sub> = 5.5 V	V <sub>I</sub> = 5.5 V			0.1			0.1	mA
I	Control inputs	V <sub>CC</sub> = 5.5 V,	V1 = 2.7 V			20			20	۸
ΙΗ	A or B ports‡	VCC = 5.5 V,	v = 2.7 v			20			20	μA
1	Control inputs		V <sub>1</sub> = 0.4 V			-0.1			-0.1	mA
۱Ľ	A or B ports‡	$V_{CC} = 5.5 V,$	V] = 0.4 V			-0.1			-0.1	ША
IO§		V <sub>CC</sub> = 5.5 V,	V <sub>O</sub> = 2.25 V	-20		-112	-30		-112	mA
			Outputs high		15	30		15	25	
ICC		V <sub>CC</sub> = 5.5 V	Outputs low		20	35		20	30	mA
			Outputs disabled		21	37		21	32	

#### electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C. <sup>‡</sup> For I/O ports, the parameters I<sub>IH</sub> and I<sub>IL</sub> include the off-state output current.

§ The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

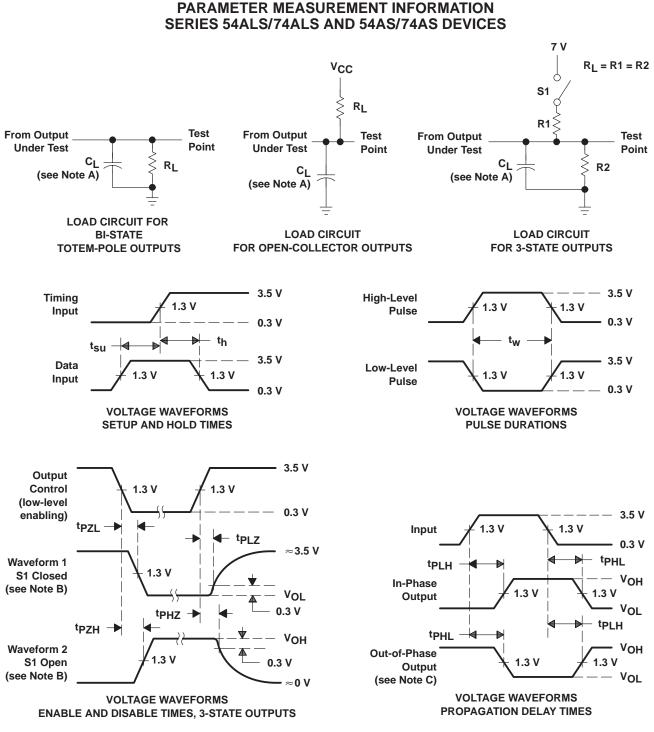
## switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V( СL R1 R2 Тд	UNIT			
			SN54AL	S243A	SN74AL	S243A	
			MIN	MAX	MIN	MAX	
<sup>t</sup> PLH	A or B	DerA	4	15	4	11	ns
<sup>t</sup> PHL	AOID	B or A	4	15	4	11	115
<sup>t</sup> PZH			7	25	7	20	ns
<sup>t</sup> PZL	OEAB	В	7	25	7	20	115
<sup>t</sup> PHZ	0545	_		16	2	14	
<sup>t</sup> PLZ	OEAB	В	3	27	3	22	ns
<sup>t</sup> PZH	0504		7	25	7	20	-
<sup>t</sup> PZL	OEBA	A	7	25	7	20	ns
<sup>t</sup> PHZ		۵	2	16	2	14	
<sup>t</sup> PLZ	OEBA	A	3	27	3	22	ns

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.



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NOTES: A. CL includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
- All input pulses have the following characteristics: PRR  $\leq$  1 MHz, t<sub>r</sub> = t<sub>f</sub> = 2 ns, duty cycle = 50%. D.
- E. The outputs are measured one at a time with one transition per measurement.

#### Figure 1. Load Circuits and Voltage Waveforms



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18-Sep-2008

## **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
84013022A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
8401302CA	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
8401302DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type
SN54ALS243AJ	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SN74ALS243A-1N	OBSOLETE	PDIP	Ν	14		TBD	Call TI	Call TI
SN74ALS243AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243AN	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS243ANE4	ACTIVE	PDIP	Ν	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74ALS243ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALS243ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54ALS243AFK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54ALS243AJ	ACTIVE	CDIP	J	14	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54ALS243AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)



<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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# TAPE AND REEL INFORMATION





# QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

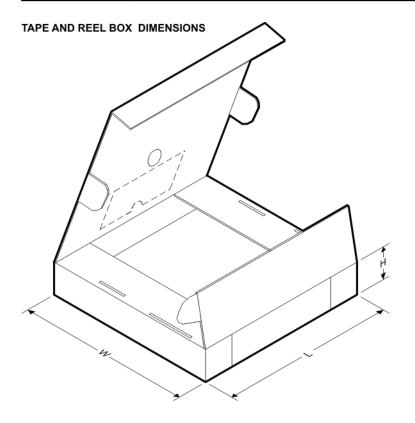


*/	Il dimensions are nominal												
	Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	SN74ALS243ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
	SN74ALS243ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



# PACKAGE MATERIALS INFORMATION

11-Mar-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALS243ADR	SOIC	D	14	2500	346.0	346.0	33.0
SN74ALS243ANSR	SO	NS	14	2000	346.0	346.0	33.0

# MECHANICAL DATA

## PLASTIC SMALL-OUTLINE PACKAGE

#### 0,51 0,35 ⊕0,25⊛ 1,27 8 14 0,15 NOM 5,60 8,20 5,00 7,40 $\bigcirc$ Gage Plane ₽ 0,25 7 1 1,05 0,55 0°-10° Δ 0,15 0,05 Seating Plane — 2,00 MAX 0,10PINS \*\* 14 16 20 24 DIM 10,50 10,50 12,90 15,30 A MAX A MIN 9,90 9,90 12,30 14,70 4040062/C 03/03

NOTES: A. All linear dimensions are in millimeters.

NS (R-PDSO-G\*\*)

**14-PINS SHOWN** 

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



MLCC006B - OCTOBER 1996

## FK (S-CQCC-N\*\*)

#### LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



J (R-GDIP-T\*\*) 14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK

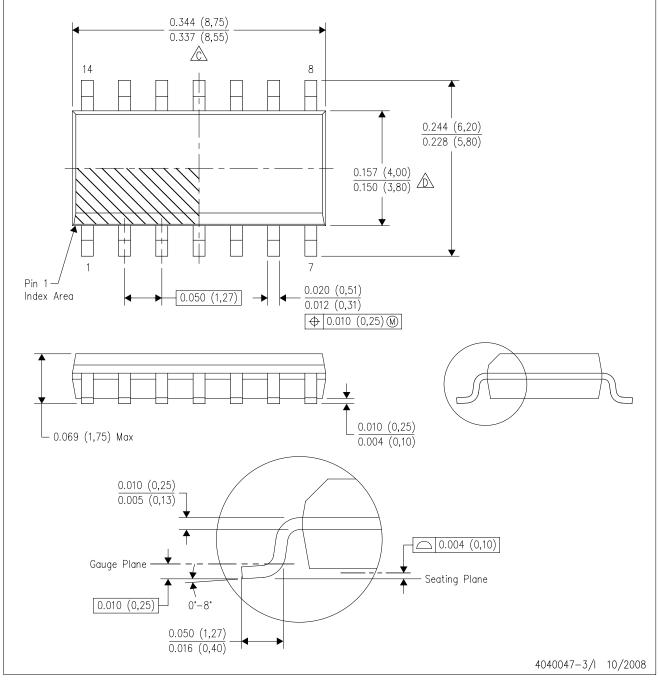


- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within MIL STD 1835 GDFP1-F14 and JEDEC MO-092AB



D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.

Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.

E. Reference JEDEC MS-012 variation AB.



# N (R-PDIP-T\*\*)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- $\triangle$  The 20 pin end lead shoulder width is a vendor option, either half or full width.

